

# SRAM MODULE 768KBit (32K x 24-Bit) Part No. HMS3224M3, HMS3224Z3

#### GENERAL DESCRIPTION

The HMS3224M3/Z3 is a high-speed static random access memory (SRAM) module containing 32,768 words organized in a x24-bit configuration. The module consists of three 32K x 8 SRAMs mounted on a 56-pin, single-sided, FR4-printed circuit board.

Writing to the device is accomplished when the chip enable (/CE) and write enable(/WE) inputs are both LOW. Data on the input/output pins (DQ0 through DQ23) of the device is written into the memory location specified on the address pins (A0 through A14).

Reading the device is accomplished by taking the chip enable (/CE) and output enable(/OE) LOW while write enable(/WE) remains HIGH. Under these conditions, the contents of the memory location specified on the address pins will appear on the input/output pins.

The input/output pins remains in a high-impedance state unless the module is selected, outputs are enabled, and write enable is HIGH.

#### **FEATURES**

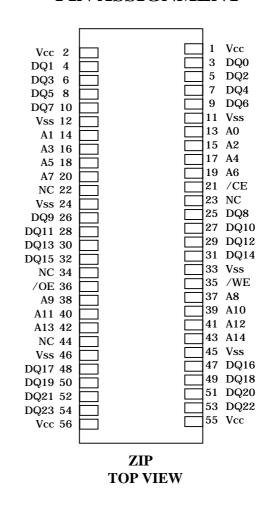
- Access times: 12, 15 and 20ns
- ◆ High-density 768Kbit design
- ◆ High-reliability, high-speed design
- Single +  $5V \pm 0.5V$  power supply
- ◆ 56-pin, low-active power design
- All inputs and outputs are TTL-compatible
- ◆ Industry-standard pinout
- ◆ FR4-PCB design
- Part identification

HMS3224M3 : 56Pin SIMM Design HMS3224Z3 : 56Pin ZIP Design

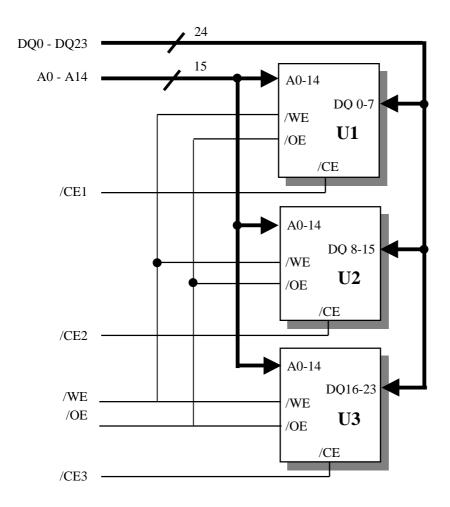
→Pin-compatible with the HMS3224M3

OPTIONS	MARKING
◆ Timing	
12ns access	-12
15ns access	-15
20ns access	-20
◆ Packages	
56-pin SIMM	M
56-pin ZIP	Z

## PIN ASSIGNMENT



## FUNCTIONAL BLOCK DIAGRAM



## TRUTH TABLE

MODE	/OE	/CE	/WE	OUTPUT	POWER
STANDBY	X	Н	X	HIGH-Z	STANDBY
NOT SELECTED	Н	L	Н	HIGH-Z	ACTIVE
READ	L	L	Н	Dout	ACTIVE
WRITE	X	L	L	Din	ACTIVE

#### **ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	RATING
Voltage on Any Pin Relative to Vss	$ m V_{IN,OUT}$	-0.5V to +7.0V
Voltage on Vcc Supply Relative to Vss	$V_{CC}$	-0.5V to +7.0V
Power Dissipation	$P_{\mathrm{D}}$	3 <b>W</b>
Storage Temperature	${ m T_{STG}}$	-65°C to +150°C
Operating Temperature	$T_{A}$	0°C to +70°C

<sup>•</sup> Stresses greater than those listed under " Absolute Maximum Ratings" may cause permanent damage to the device.

This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## **RECOMMENDED DC OPERATING CONDITIONS** ( $T_A=0$ to 70 ° C )

PARAMETER	SYMBOL	MIN	TYP.	MAX
Supply Voltage	$V_{CC}$	4.5V	5.0V	5.5V
Ground	$V_{SS}$	0	0	0
Input High Voltage	$V_{ m IH}$	2.2	-	Vcc+0.5V**
Input Low Voltage	V <sub>IL</sub>	-0.5*	-	0.8V

<sup>\*</sup>  $V_{IL}(Min.) = -2.0V$  (Pulse Width  $\leq 10ns$ ) for  $I \leq 20$  mA

## DC AND OPERATING CHARACTERISTICS (1)(0°C $\leq$ $T_{A} \leq$ 70 °C ; Vcc = 5V $\pm$ 0.5V )

PARAMETER	TEST CONDITIONS	SYMBO L	MIN	MAX	UNITS
Input Leakage Current	$V_{IN} = Vss \text{ to } Vcc$	$IL_I$	-6	6	μΑ
Output Leakage Current	$\overline{CE} = V_{IH \text{ or }} \overline{OE} = V_{IH} \text{ or } \overline{WE} = V_{IL}$ $V_{OUT} = V_{SS} \text{ to } V_{CC}$	$IL_0$	-6	6	μΑ
Output High Voltage	$I_{OH} = -4.0 \text{mA}$	$V_{OH}$	2.4		V
Output Low Voltage	$I_{OL} = 8.0 \text{mA}$	V <sub>OL</sub>		0.4	V

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<sup>\*\*</sup>  $V_{IH}(Min.) = Vcc+2.0V$  (Pulse Width  $\leq 10ns$ ) for  $I \leq 20$  mA

<sup>\*</sup> Vcc=5.0V, Temp=25 °C

## DC AND OPERATING CHARACTERISTICS (2)

				MAX		
DESCRIPTION	TEST CONDITIONS	SYMBOL	-12	-15	-20	UNIT
Power Supply Current: Operating	Min. Cycle, 100% Duty /CE= $V_{IL}$ , $V_{IN}$ = $V_{IH}$ or $V_{IL}$ , $I_{OUT}$ =0mA	l <sub>CC</sub>	495	450	420	mA
Power Supply	Min. Cycle, /CE=V <sub>IH</sub>	$l_{SB}$	120	120	120	mA
Current :Standby	f=0MHZ, /CE $\geq$ V <sub>CC</sub> -0.2V, V <sub>IN</sub> $\geq$ V <sub>CC</sub> -0.2V or V <sub>IN</sub> $\leq$ 0.2V	$l_{SB1}$	6	6	6	mA

## **CAPACITANCE**

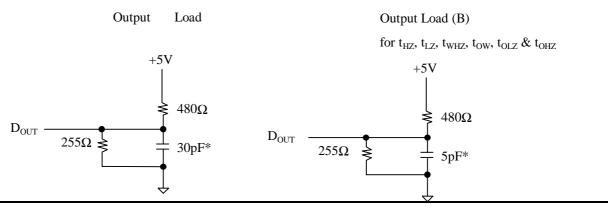
DESCRIPTION	TEST CONDITIONS	SYMBOL	MAX	UNIT
Input /Output Capacitance	V <sub>I/O</sub> =0V	$C_{I\!/O}$	24	pF
Input Capacitance	$V_{IN}=0V$	$C_{IN}$	21	pF

<sup>\*</sup> NOTE: Capacitance is sampled and not 100% tested

## $\label{eq:characteristics} \textbf{AC CHARACTERISTICS} \ (0^{o}\text{C} \leq \text{T}_{A} \leq 70 \ ^{o}\text{C} \ ; \ \text{Vcc} = 5\text{V} \pm 0.5\text{V}, \ \text{unless otherwise specified)}$

### TEST CONDITIONS

PARAMETER	VALUE
Input Pulse Level	0 to 3V
Input Rise and Fall Time	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	See below



## **READ CYCLE**

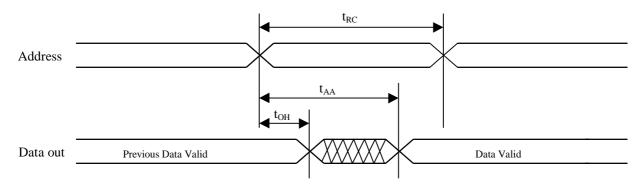
2.2.2.2		-12		-15		-20		
PARAMETER	SYMBOL	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
Read Cycle Time	t <sub>RC</sub>	12		15		20		ns
Address Access Time	$t_{AA}$		12		15		20	ns
Chip Select to Output	$t_{CO}$		12		15		20	ns
Output Enable to Output	$t_{OE}$		6		7		9	ns
Output Enable to Low-Z Output	t <sub>OLZ</sub>	0		0		0		ns
Chip Enable to Low-Z Output	$t_{LZ}$	3		3		3		ns
Output Disable to High-Z Output	t <sub>OHZ</sub>	0	6	0	7	0	10	ns
Chip Disable to High-Z Output	$t_{\rm HZ}$	0	6	0	7	0	10	ns
Output Hold from Address Change	t <sub>OH</sub>	3		3		3		ns
Chip Select to Power Up Time	$t_{\mathrm{PU}}$	0		0		0		ns
Chip Select to Power Down Time	t <sub>PD</sub>		12		15		20	ns

## WRITE CYCLE

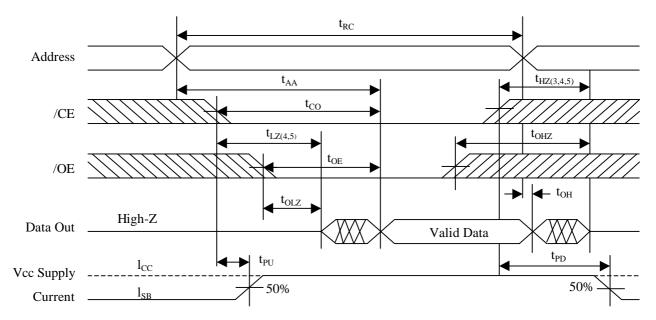
		-]	-12		-15		-20	
PARAMETER	SYMBOL	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
Write Cycle Time	$t_{ m WC}$	12		15		20		ns
Chip Select to End of Write	t <sub>CW</sub>	9		11		13		ns
Address Set-up Time	t <sub>AS</sub>	0		0		0		ns
Address Valid to End of Write	t <sub>AW</sub>	9		12		13		ns
Write Pulse Width	$t_{\mathrm{WP}}$	9		12		13		ns
Write Recovery Time	$t_{ m WR}$	12		0		0		ns
Write to Output High-Z	$t_{ m WHZ}$	0	6	0	8	0	8	ns
Data to Write Time Overlap	$t_{\mathrm{DW}}$	7		8		10		ns
Data Hold from Write Time	t <sub>DH</sub>	0		0		0		ns
End of Write to Output Low-Z	t <sub>OW</sub>	0		0		0		ns

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#### TIMING DIAGRAMS



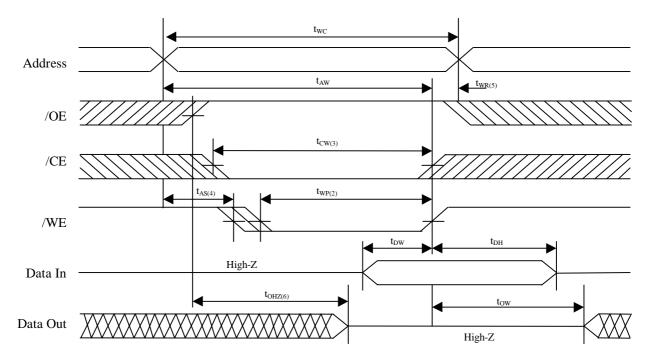
## TIMING WAVEFORM OF READ CYCLE ( $/WE=V_{IH}$ )



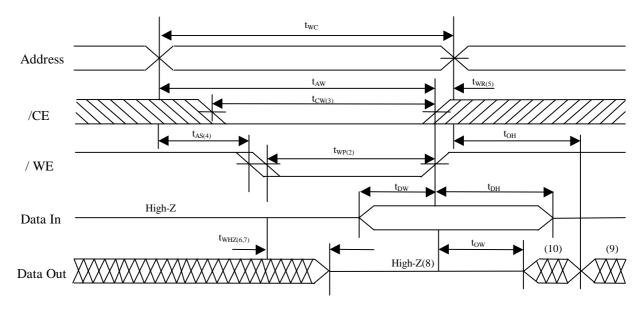
### Notes (Read Cycle)

- 1. /WE is high for read cycle.
- 2. All read cycle timing is referenced from the last valid address to the first transition address.
- 3.  $t_{HZ}$  and  $t_{OHZ}$  are defined as the time at which the outputs achieve the open circuit condition are not referenced to  $V_{OH}$  or  $V_{OL}$  levels.
- 4. At any given temperature and voltage condition,  $t_{HZ}$  (max.) is less than  $t_{LZ}$  (min.) both for a given device and from device to device.
- 5. Transition is measured  $\pm$  200mV from steady state voltage with Load (B). This parameter is sampled and not 100% tested.
- 6. Device is continuously selected with  $/CE = V_{IL}$ .
- 7. Address valid prior to coincident with /CE transition low.

### TIMING WAVEFORM OF WRITE CYCLE (/OE = Clock )



### TIMING WAVEFORM OF WRITE CYCLE (/OE Low Fixed )



## Notes(Write Cycle)

- 1. All write cycle timing is referenced from the last valid address to the first transition address.
- 2. A write occurs during the overlap of a low /CE and a low /WE. A write begins at the latest transition among /CE going low and /WE going low: A write ends at the earliest transition among /CE going high and /WE going high.  $t_{WP}$  is measured from the beginning of write to the end of write.

- 3. t<sub>CW</sub> is measured from the later of /CE going low to the end of write.
- 4. t<sub>AS</sub> is measured from the address valid to the beginning of write.
- 5. t<sub>WR</sub> is measured from the end of write to the address change. t<sub>WR</sub> applied in case a write ends as /CE, or /WE going high.
- 6. If /OE,/CE and /WE are in the read mode during this period, the I/O pins are in the output low-Z state. Inputs of opposite

phase of the output must not be applied because bus contention can occur.

7. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write

cycle.

- 8. If /CE goes low simultaneously with /WE going low or after /WE going low, the outputs remain high impedance state.
- 9. D<sub>OUT</sub> is the read data of the new address.
- 10. When /CE is low: I/O pins are in the output state. The input signals in the opposite phase leading to the output should not be applied.

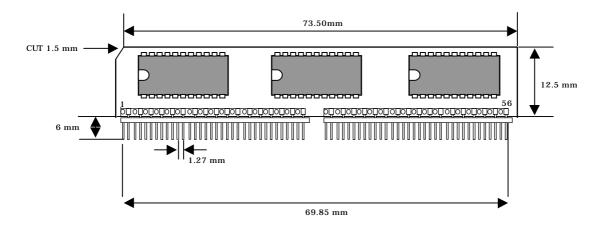
### **FUNCTIONAL DESCRIPTION**

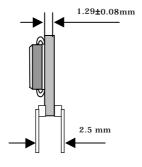
/CE	/WE	/OE	MODE	I/O PIN	SUPPLY CURRENT
Н	X*	X	Not Select	High-Z	1 <sub>SB</sub> , 1 <sub>SB1</sub>
L	Н	Н	Output Disable	High-Z	$l_{CC}$
L	Н	L	Read	$\mathrm{D}_{\mathrm{OUT}}$	$l_{CC}$
L	L	X	Write	$D_{IN}$	l <sub>CC</sub>

Note: X means Don't Care

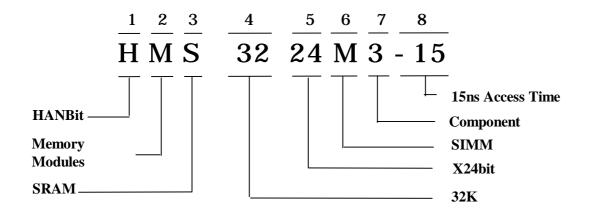
## PACKAGING INFORMATION

## **ZIP Design**





#### **ODERING INFORMATION**



1. - Product Line Identifier HANBit Technology ------ H 2. - Memory Modules 3. - **SRAM** 4. - Depth: 32K 5. - Width: x 24bit 6. - Package Code SIMM ----- M ----- Z **ZIP** 7. – Number of Memory Components 8. - Access time 10 ----- 10ns 12 ------ 12ns 15 ----- 15ns 17 ------ 17ns 20 ------ 20ns